<table>
<thead>
<tr>
<th>Device evaluation</th>
<th>MATERIAL PERFORMANCE TEST RESULTS (on the basis of AEC-Q100)</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>includes integrated circuits (e.g. AEC-Q100, radiation, voltage regulation, cool pass device, logic device, scaling device...)</td>
</tr>
<tr>
<td></td>
<td>additional to AEC-Q10x</td>
</tr>
</tbody>
</table>

### Remarks / Comments:

1.  For integrated circuits or discrete semiconductors select below:
2.  PCN number
3.  16576

### Additional References:

**A / B / C**

- **Evaluation level**
- **Type of change**
  - **No**
  - **Yes**

### Notes:

- **Remarks**
  - **Type of change**
  - **No**
  - **Yes**

### Evaluation Matrix:

|            |         |   |   |   |   |   |   |   |   |   |   |   |   |   |   |   |   |   |   |   |   |   |   |   |   |   |   |   |   |   |   |   |   |

### Additional Information:

- **Examples to explain**
- **Wording design is different for IC e.g. change of ESD structure**
- **Design optimization = modification to adapt to changes in the specified process window.**
- **Change in leadframe dimensions which has impact to the specified electrical parameter acc. data sheet or specification (e.g. heat sink, pin dimensions, die paddle size, ...)**
- **Change in leadframe dimensions**
- **Investigation for ESD is only necessary if internal ground and power supply connection of leadframe is affected.**
- **Change in leadframe dimensions**
- **EMC behavior is influenced if electrical connection to leadframe is affected (non conducting to conducting). Otherwise verification on component level is sufficient.**
- **Change of mold compound**
- **Has to be discussed with Pb-Matrix team (ESD influence). R (EMC): Influence expected if number of bond contacts > 100 or significant change of bond wire change (>30%).**
- **Change of bond wire material / diameter**
- **Material, diameter, change in process technique e.g. change from Au to Cu material**
- **Change of die attach material (e.g. soft solder, **Material, diameter, change in process technique e.g. change from Au to Cu material**
- **Change of mold compound**
- **Has to be discussed with Pb-Matrix team (ESD influence). R (EMC): Influence expected if number of bond contacts > 100 or significant change of bond wire change (>30%).**
- **Change of bond wire material / diameter**
- **Material, diameter, change in process technique e.g. change from Au to Cu material**
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